

Description

Features

- Trench LV MOSFET technology
- Fast switching
- High density cell design for low $R_{ds(on)}$

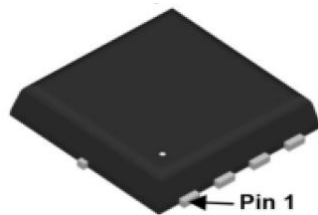
Application

- High current load application
- Load Switch
- Power management

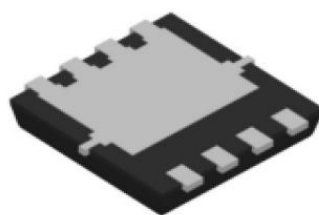
V_{DS}	40	V
$R_{ds(on),typ}@V_{gs}=10V$	5.8	m Ω
$R_{ds(on),typ}@V_{gs}=4.5V$	7	m Ω
I_D	70	A



Top View

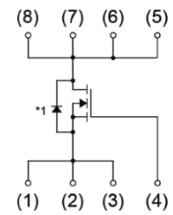


Bottom View



Pin Configuration

- (1) Source
(2) Source
(3) Source
(4) Gate
(5) Drain
(6) Drain
(7) Drain
(8) Drain
*1 Body Diode



Package Marking and Ordering Information

Part	Marking	Package	Packing	Reel Size	Tape Width	Qty
CMT4070K	T4070K	PDFN3.3*3.3	Reel	NA	NA	5000pcs

Key Performance Parameters

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_c=25^\circ C$	Continuous Drain Current, $V_{GS}=10V$	70	A
$I_D@T_c=100^\circ C$	Continuous Drain Current, $V_{GS}=10V$	44	A
I_{DM}	Pulsed Drain Current ¹	280	A
EAS	Single Pulse Avalanche Energy ⁴	144	mJ
$PD@T_c=25^\circ C$	Total Power Dissipation	37	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_j	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Typ	Max	Units
R _{θJA}	Thermal Resistance Junction-Ambient	36	42	°C/W
R _{θJC}	Thermal Resistance Junction-Case	2.9	3.4	°C/W

Electrical Characteristics (T_J=25 °C, Unless otherwise noted)

Symbol	Parameter	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
BVDSS	Drain-Source Breakdown Voltage	40	--	--	V	V _{GS} =0V, I _D =250uA
R _{DS(ON)}	Static Drain-Source On-Resistance	--	5.8	7	mΩ	V _{GS} =10V, I _D =20A
		--	7	9.5		V _{GS} =4.5V, I _D =10A
V _{GS(th)}	Gate Threshold Voltage	1.0	1.6	2.5	V	V _{GS} =V _{DS} , I _D =250uA
IDSS	Drain-Source Leakage Current	--	--	1	uA	V _{DS} =40V, V _{GS} =0V, T _J =25°C
		--	--	10	uA	V _{DS} =32V, V _{GS} =0V, T _J =125°C
IGSS	Gate-Source Leakage Current	--	--	±100	nA	V _{GS} =±20V, V _{DS} =0V
Qg	Total Gate Charge ^{2,3}	--	49.2	--	nC	V _{DS} =20V, V _{GS} =10V, I _D =30A
Qgs	Gate-Source Charge ^{2,3}	--	9.5	--		
Qgd	Gate-Drain Charge ^{2,3}	--	13	--		
Td(on)	Turn-On Delay Time ^{2,3}	--	12	--	ns	V _{DD} =20V, V _{GS} =10V, R _G =3Ω I _D =30A
T _r	Rise Time ^{2,3}	--	29	--		
Td(off)	Turn-Off Delay Time ^{2,3}	--	60	--		
T _f	Fall Time ^{2,3}	--	16	--		
Ciss	Input Capacitance	--	3778	--	pF	V _{DS} =20V, V _{GS} =0V, f=1MHz
Coss	Output Capacitance	--	267	--		
Crss	Reverse Transfer Capacitance	--	224	--		

Diode Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Units
I _S	Continuous Source Current	VG=VD=0V, Force Current	--	--	70	A
I _{sm}	Pulsed Source Current		--	--	280	A
T _{rr}	Body Diode Reverse Recovery Time	IF=30A, di/dt=100A/us	--	16	--	ns
Q _{rr}	Body Diode Reverse Recovery Charge		--	10	--	nC
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =30A, T _J =25°C	--	--	1.2	V

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.
4. The EAS data shows Max. rating. The test condition is V_{DD}=20V, V_{GS}=10V, L=0.5mH.

Typical Performance Characteristics

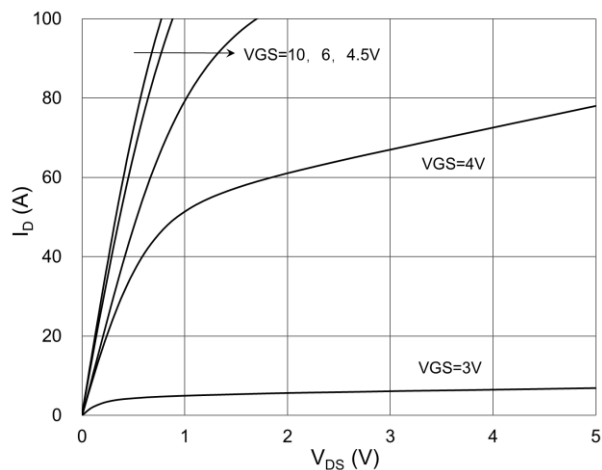
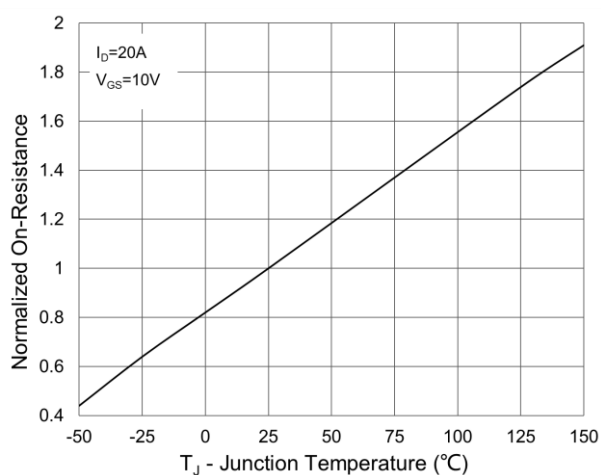
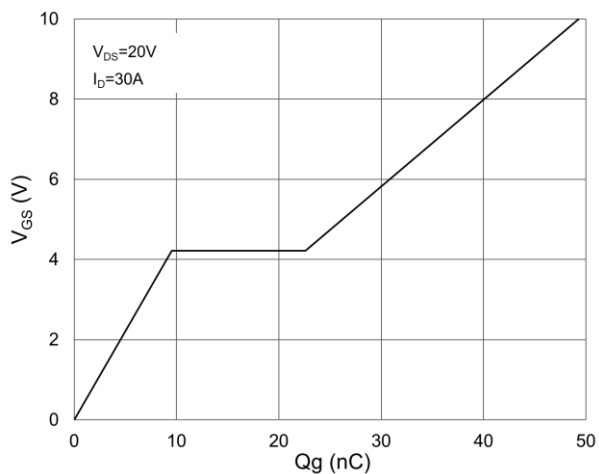
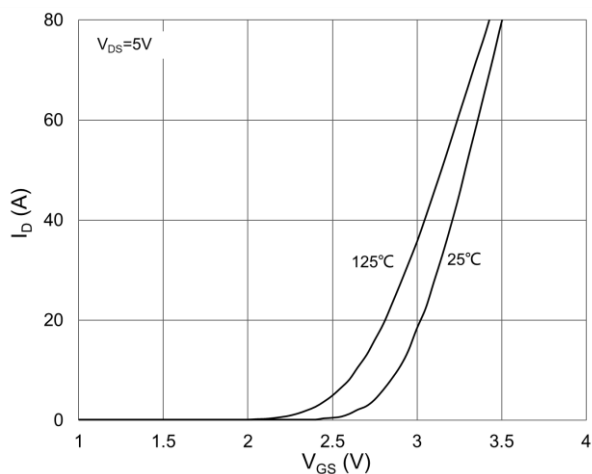
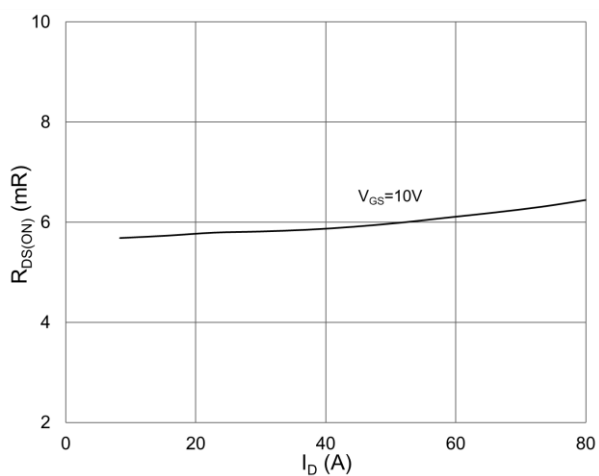
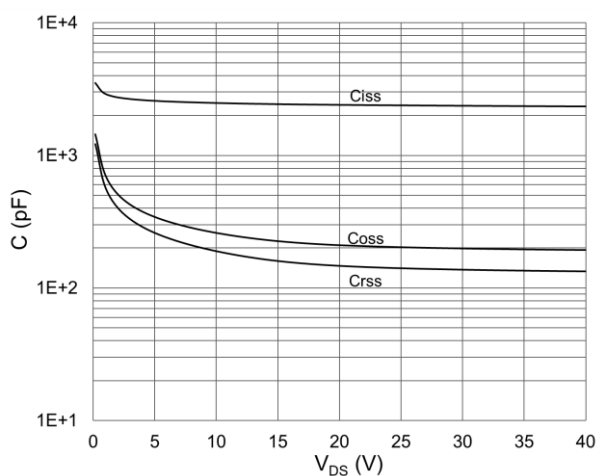
Fig1 Output Characteristics

Fig2 Normalized $R_{DS(on)}$ vs. T_J

Fig3 Gate Charge Waveform

Fig4 Transfer Characteristics

Fig5 $R_{DS(on)}$ vs. Drain Current and Gate Voltage

Fig6 Capacitance Characteristics


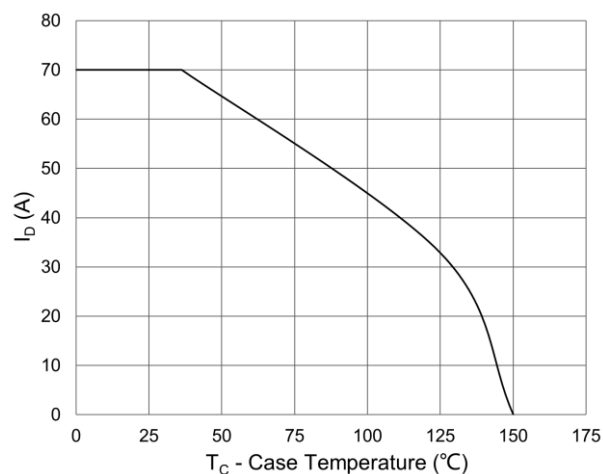
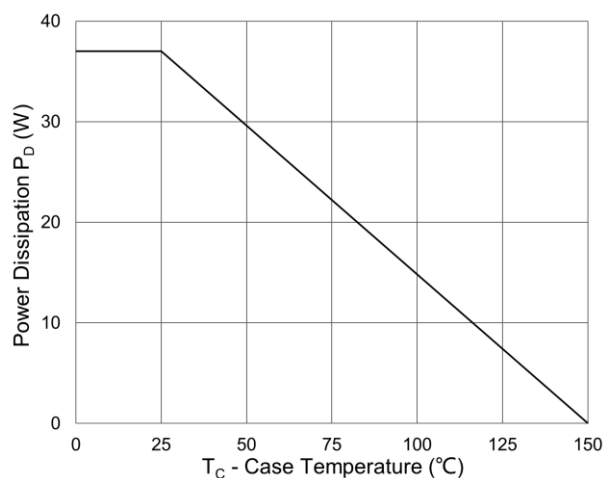
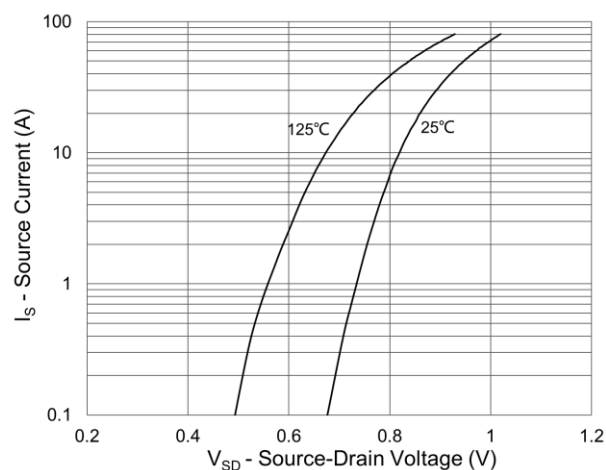
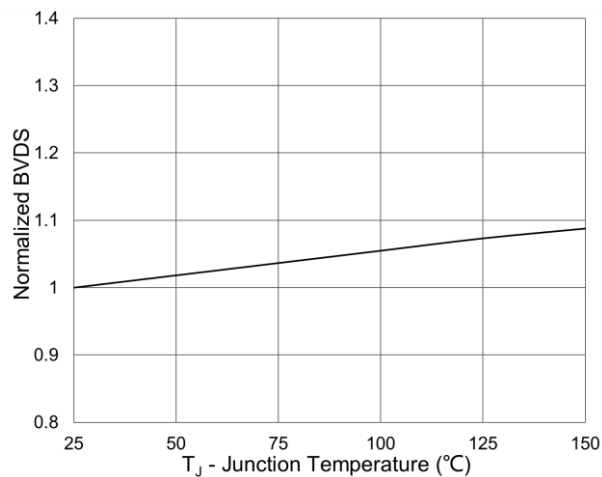
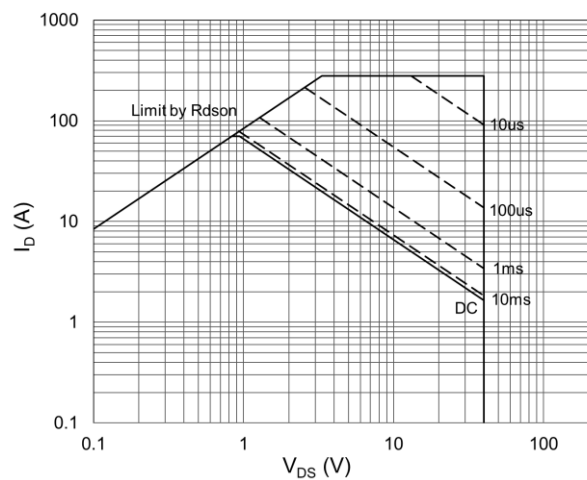
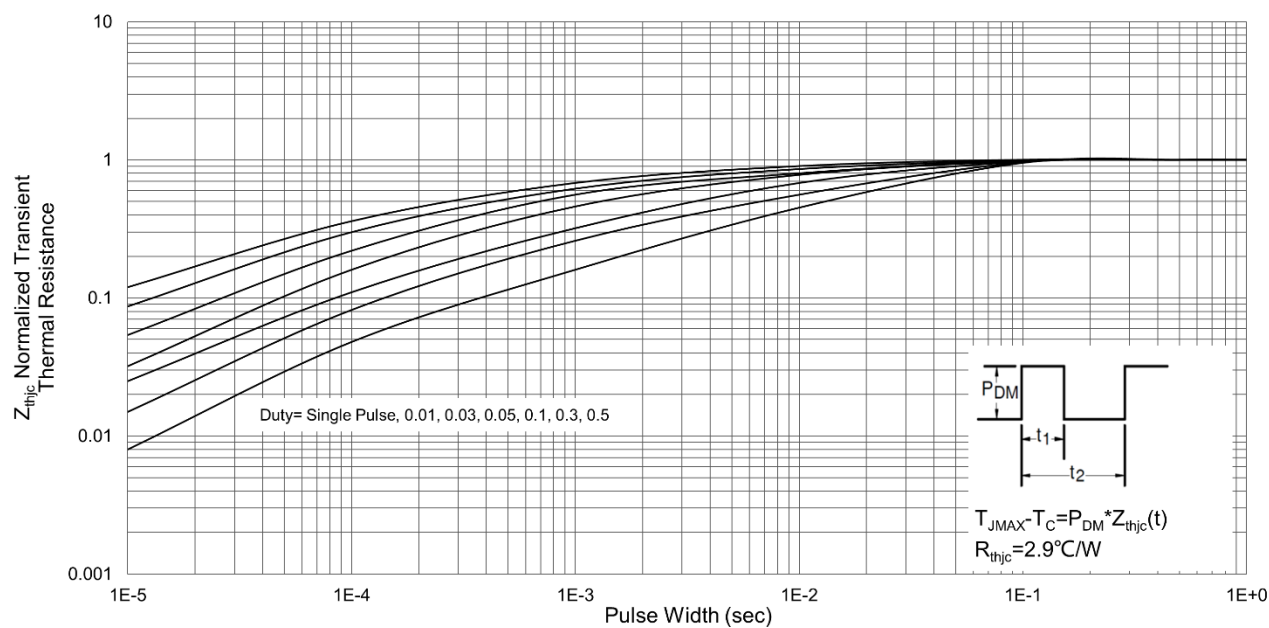
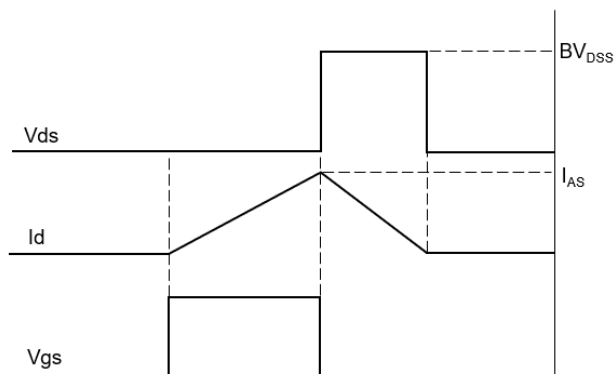
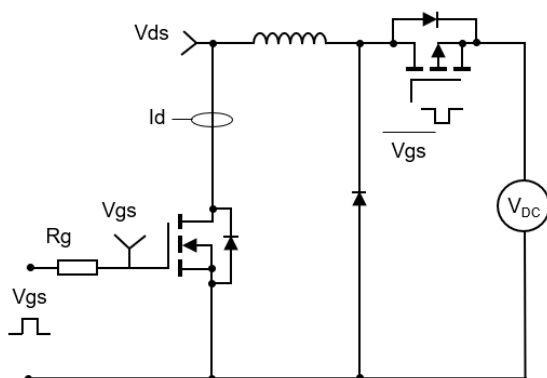
Fig7 Drain Current Derating

Fig8 Power Dissipation

Fig9 Source-Drain Diode Forward Characteristics

Fig10 Normalized Breakdown Voltage vs. T_J

Fig11 Maximum Safe Operation Area


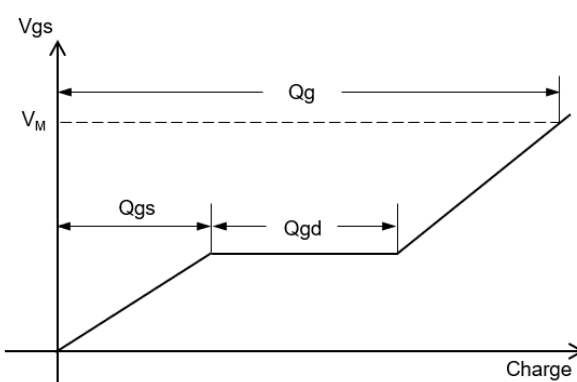
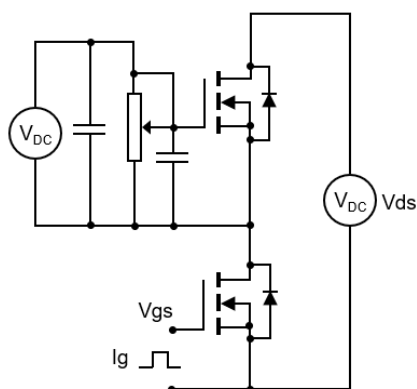
Fig12 Normalized Transient Impedance


Test Circuit & Waveform

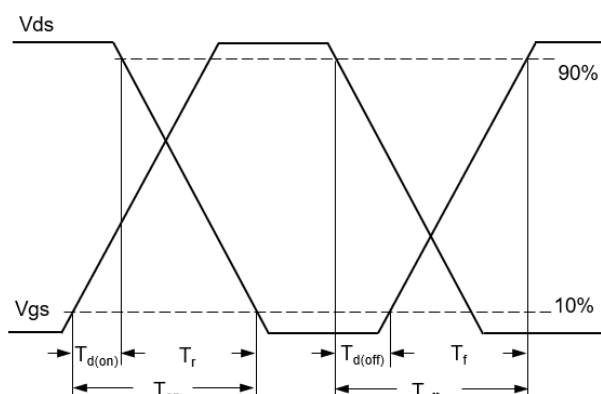
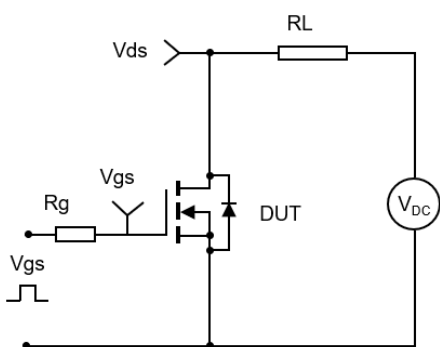
1. Unclamped Inductive Switching Test Circuit & Waveform



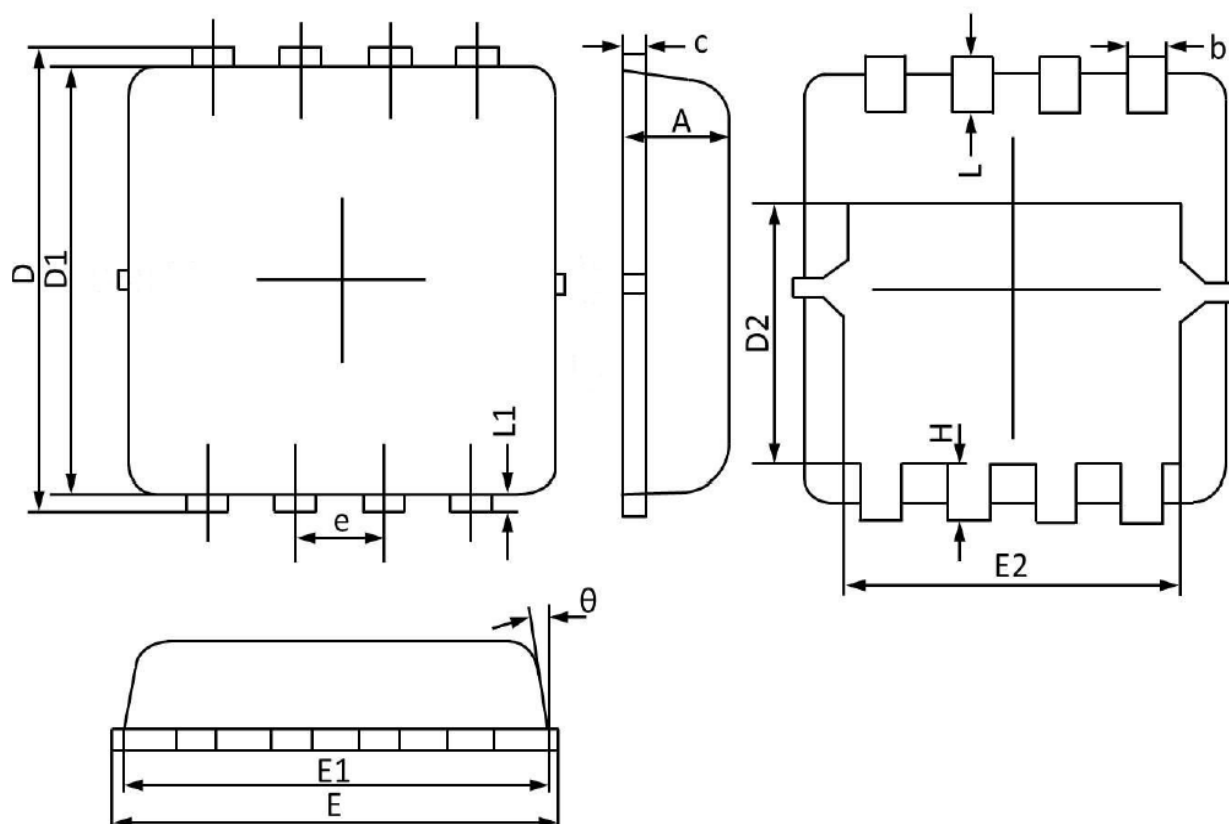
2. Gate Charge Test Circuit & Waveform



3. Resistive Switching Test Circuit & Waveform



PDFN3.3*3.3 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.240	0.014	0.009
c	0.250	0.100	0.010	0.004
D	3.450	3.050	0.136	0.120
D1	3.200	2.900	0.126	0.114
D2	1.850	1.350	0.073	0.053
E	3.400	3.000	0.134	0.118
E1	3.250	2.900	0.128	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.500	0.300	0.020	0.012
L	0.500	0.300	0.020	0.012
L1	0.200	0.070	0.008	0.003
θ	12°	0°	12°	0°